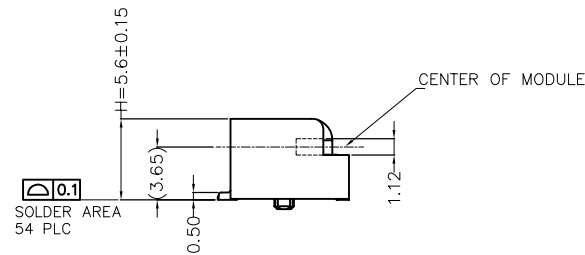
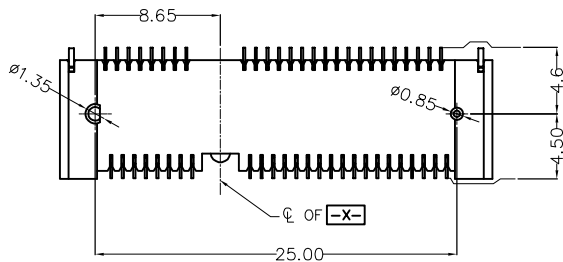
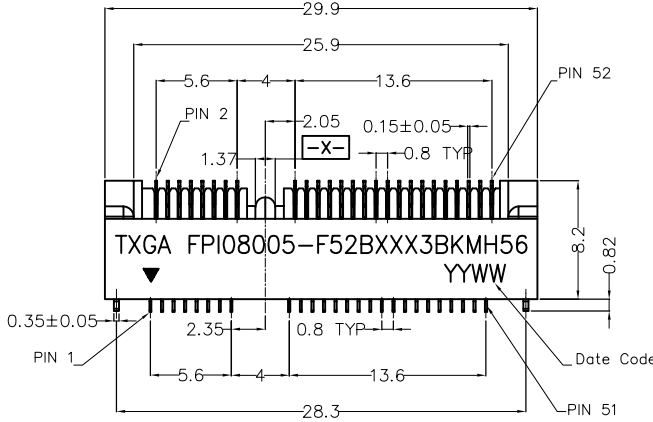


| REV | LOCATIONS | DESCRIPTION | DATE | REVISER | APPD |
|-----|-----------|-------------|------|---------|------|
| | | | | | |

SPECIFICATIONS

Electrical
 Current Rating: 0.5A AC(rms)/DC
 Voltage Rating: 50V AC(rms)/DC
 Contact Resistance: 55mΩ Max
 Insulation Resistance: 500MΩ Min
 Withstanding Voltage: 300V AC r.m.s
 Temperature Range-Operating: -40°C ~ +80°C

Material
 Housing: LCP (UL 94V-0) Black
 Contact: Copper Alloy/ Selected gold plated on contact area,
 1u" Min. gold plated on solder tails
 Pegs: Copper Alloy/ 120u" Min. Matte Tin Plated



Ordering Information

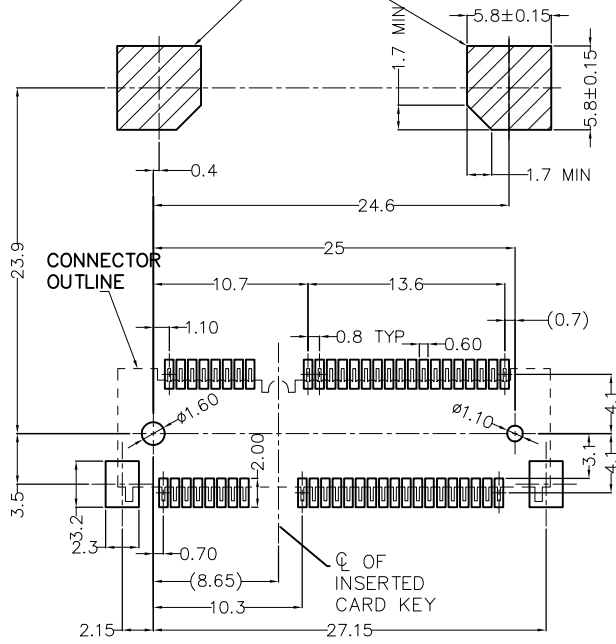
FPI 080 05 - F 52 B 1 XX 3 BK M H56
 1 2 3 4 5 6 7 8 9 10 11 12

| | | | | | | |
|--|------------------------------------|----------------------------|------------------------|-------------------------------------|------------------------------|----------------------------|
| 1 Category FPI-MINI PCI | 2 Series Number 080-Pitch0.80mm | 3 Distinction No. 05 | 4 Type F-Female | 5 Circuits 52 | 6 Entry Angle B-90° Angle | 7 Plating 1-Gold Plated |
| 8 thickness of Gold Plating 00-Gold Flash 10-10u" 30-30u" | 9 Material-Resin 3-LCP | 10 Color-Resin BK-Black | 11 Packaging M-Reel | 12 Connector Height(H) H56-5.6mm | | |

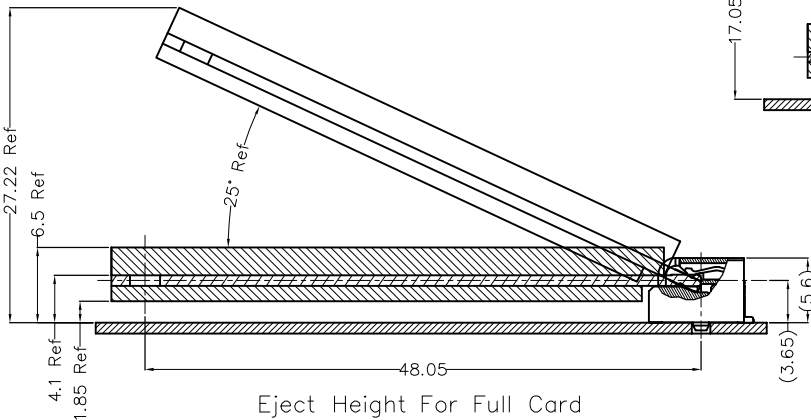
| | | | | | | | | | |
|-------------------------------|---------------------------------------|------------|-----------------------|-------------------|--|----------------------|--|-------|---------------|
| <p>THIRD ANGLE PROJECTION</p> | GENERAL TOLERANCES (UNLESS SPECIFIED) | | APPROVE BY LEO | DATE 20/JUL/24 | PART NO. FPI08005-F52BXXX3BKM H56 | ITEM NO. FPI08005 | <p>Building Technology Cornerstone</p> | | |
| | X. ±0.30 | X.* ±5° | CHECKED BY GISELLE | DATE 20/JUL/24 | TITLE MINI PCI Express (H5.6mm) Pitch 0.8mm 90° Angle | | | REV 0 | SHEET NO. 1/2 |
| | X.X ±0.20 | X.X* ±2° | DRAWN BY MATT | DATE 20/JUL/24 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |
| SCALE 5:1 | SIZE A4 | X.XX ±0.15 | X.XX* ±1° | | | | | | |
| X.XXX ±0.10 | X.XXX* ±0.5° | | | | | | | | |

| REV | LOCATIONS | DESCRIPTION | DATE | REVISER | APPD |
|-----|-----------|-------------|------|---------|------|
| | | | | | |

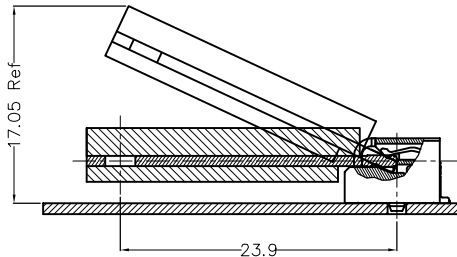
COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



Recommended P.C.Board Layout For Half Card
General tolerances: ±0.05mm

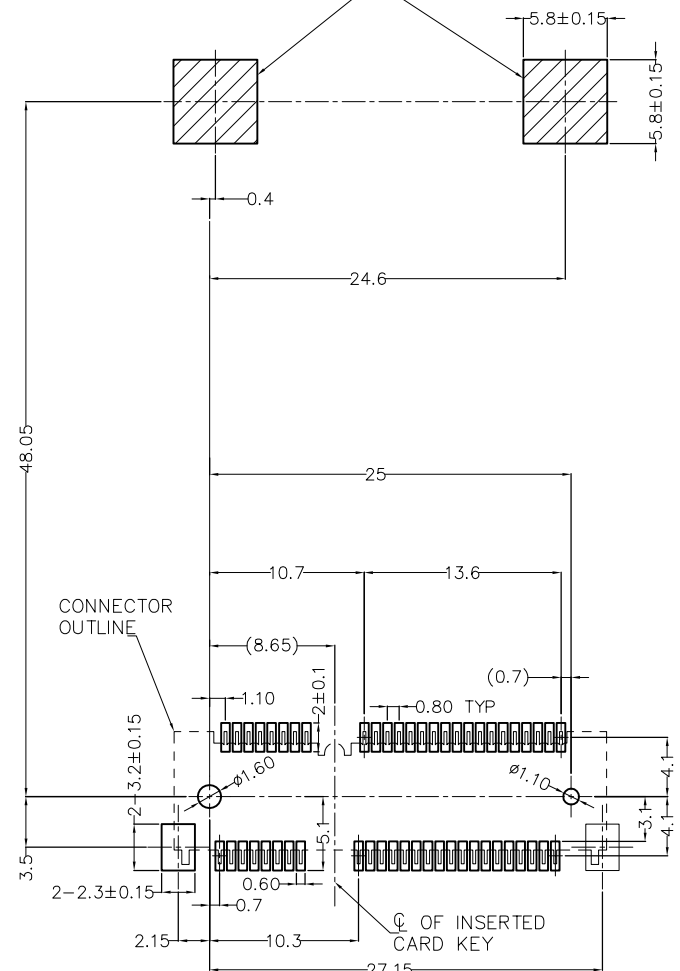


Eject Height For Full Card



Eject Height For Half Card

COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



Recommended P.C.Board Layout For Full Card
General tolerances: ±0.05mm

| | | | | | | | |
|-------------------------------|--|-------------|-----------------------|-------------------|--|----------------------|-------------------------------------|
| THIRD ANGLE PROJECTION | GENERAL TOLERANCES (UNLESS SPECIFIED) | | APPROVE BY LEO | DATE 20/JUL/24 | PART NO. FPI08005-F52BXXX3BKMHS6 | ITEM NO. FPI08005 | Building Technology Cornerstone |
| | X. ±0.30 | X.* ±5° | CHECKED BY GISELLE | DATE 20/JUL/24 | TITLE MINI PCI Express (H5.6mm) Pitch 0.8mm 90° Angle | | |
| DESIGN UNITS METRIC(mm) | X.X ±0.20 | X.X* ±2° | DRAWN BY MATT | DATE 20/JUL/24 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |
| SCALE 5:1 | SIZE A4 | X.XX ±0.15 | | | | | |
| | | X.XXX ±0.10 | | | | | |